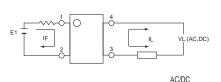
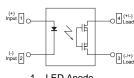


Parameter	Symbol	Rating	Units	
Load Voltage	VL	400	V	
Load Current	lL .	0.12	Α	
On-Resistance	Ron	20	Ω	
I/O Breakdown Voltage	V/IO	5000	Vrms	





- 1. LED Anode
- 2. LED Cathode
- 3.4. Drain(MOS FET)



#### **APSEMI PhotoRelays**

APSEMI Photorelays are the most reliable, technically advanced logic-to-power interface devices. Their basic function is to take a low current signal from a microprocessor to control the switching of both AC and DC loads, while providing an isolation barrier between logic and power. While this function is common to all relays, Photorelays provide distinct advantages over their mechanical counterparts including:

- Long life (No limit on mechanical and electrical
- lifetime)Bounce-free switching
- Higher speed and high frequency switching
- Higher sensitivity (less power consumption)
- Immunity to EMI or RFI

- No have voltaic arc, bounce, and noise More
- resistant to vibration and impact AC or DC load
- switching
- Small package size

#### **Function**

APSEMI PhotoRelays operate by taking a low level input current (<5mA) that energizes an input Infrared LED, which is optically-coupled to a Photo-diode array chip. This IC in turn generates a photo voltage that powers two MOSFETs typically connected in a source-to-source con | guration, allowing for both AC and DC output loads. Photorelay basically move photons to accomplish their switching function, they incur no mechanical wear and tear, providing consistent reliable switching.

# **Applications**

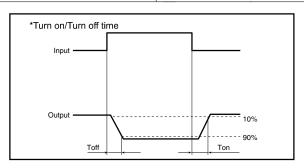
These advantages make APSEI Photorelays the ideal choice for:

- Telecom/Datacom switching
- Multiplexers
- Meter reading systems
- Data acquisition
- Medical equipment
- Battery monitoring
- I/O Sub-Systems

- Robotics
- Aerospace
- Home/Safety security systems
- **Process Control**
- **Energy Management**
- Reed Relay EMR Replacement
- Programmable Controllers

#### **TPYES**

Category Contract Category Coad voltage Coad current	Output rating					
	Package	Part No.	Packing quantity			
AC/DC	400)/	0.404	DIP-4	APY414E	50pcs/tube	
AC/DC 400V	0.12A	SMD-4	APY414EH	1000pcs/1reel		





# Absolute Maximum Ratings (Ta = 25°C)

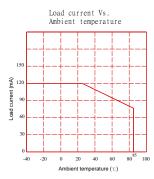
	Item	Symbol	Value	Units	Note
Continuous LED Current		l <sub>F</sub>	50	mA	
Input	Peak LED Current	<b>I</b> FP	500	mA	f=100Hz, duty=1%
	LED Reverse Voltage	VR	5	V	
	Input Power Dissipation	Pln	75	mW	
Output	Load Voltage	VL	400	V(AC peak or DC)	
	Load Current	lι	0.12	Α	
	Peak Load Current	Peak	0.3	А	100ms(1 pulse)
	Output Power Dissipation	Pout	500	mW	
Total Powe	er Dissipation	Рт	550	mW	
I/O Breako	lown Voltage	V <sub>I/O</sub>	5000	Vrms	RH=60%, 1min
Operating	Temperature	Topr	-40 to +85	°C	
Storage Te	Storage Temperature		-40 to +100	°C	
Pin Solder	ing Temperature	Tsol	260	°C	10 sec max.

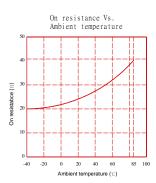
Electrical Specifications (Ambient Temperature: 25°C)

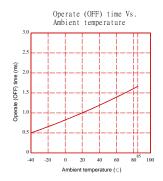
	Item	Symbol	MIN.	TYP.	MAX.	Units	Conditions
	LED Forward Voltage	VF		1.2	1.4	V	I⊧=10mA
Input	Operation LED Current	I <sub>F</sub> on		0.5	3.0	mA	
	Recovery LED Current	I <sub>F off</sub>		0.35	0.5	mA	
	Recovery LED Voltage	V <sub>F</sub> off	0.5			V	
Output	On-Resistance	Ron		20	50	Ω	I⊧=0mA,I∟=100mA, Time to flow is within 1 sec.
	Off-State Leakage Current	Leak			1.0	uA	V <sub>L</sub> =Rating
	Output Capacitance	Cout		165		pF	V∟=0, f=1MHz
Transmis	Turn-On Time	Ton		0.02	1.0	ms	I⊧=5mA, I∟=100mA,
sion	Turn-Off Time	Toff		0.5	3.0	ms	
Coupled	I/O Isolation Resistance	Rı/o	10 <sup>10</sup>			Ω	DC500V
Coupled	I/O Capacitance	C <sub>I/O</sub>		0.8	1.5	pF	f=1MHz

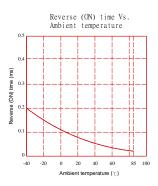
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value): IF ≥5mA and ≤30mA

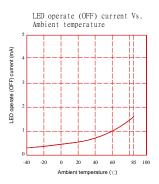
# **Engineering Data**

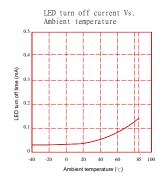


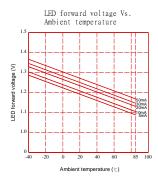


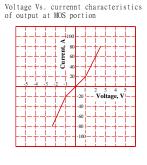


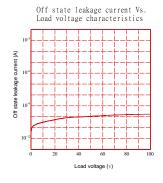


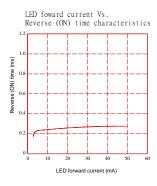


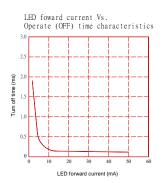


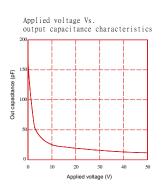








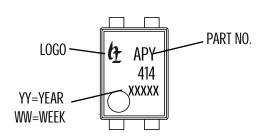






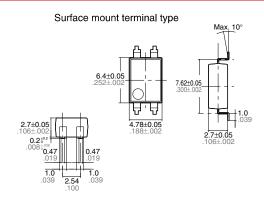
# Dimensions and SMD-4 Package Unit: mm

## Marking



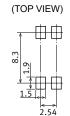
## Lable





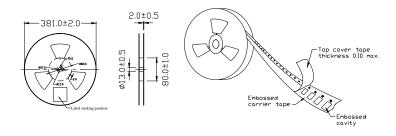
Terminal thickness: t = 0.2General tolerance: ±0.1

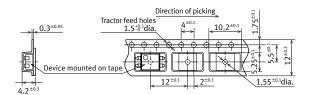
# Recommended mounting pad



Tolerance: ±0.1

## Tape dimensions (tape reel)





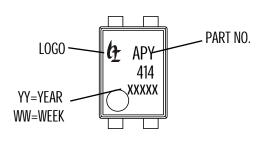
www.a-semi.com



# **Dimensions and DIP-4 Package**

Unit: mm

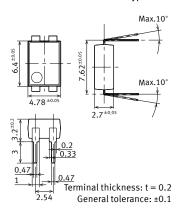
# Marking



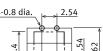
Lable



#### Surface mount terminal type



# PC board pattern (BOTTOM VIEW)



Tolerance: ±0.1

## Tape dimensions (tape reel)

# DIP type

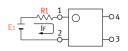
Devices are packaged in a tube so that pin No. 1 is on the stopper B side. Observe correct orientation when mounting them on PC boards.

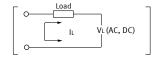




# **Using Methods**

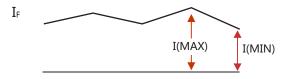
Examples of resistance value to control LED forward current (IF=5mA)





R1 (Approx)
300 Ω
600 Ω
1.9ΚΩ
4.1K Ω

LED forward current must be more than 5mA, at I(MIN), and less than 30mA, at I(MAX).



## **Recommended Operating Conditions**

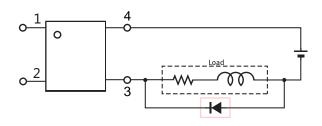
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value):

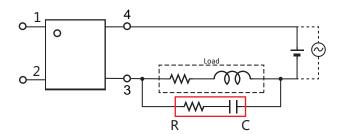
Characteristic	Symbol	Min	Тур.	Max	Unit
Forward current	IF	5.0	7.0	30	mA

#### **Protection Circuit**

Clamp diode is connected in parallel with the load. Absorb capacity with external diode.

CR Snubber is connected in parallel with the load. Absorb capacity with buffer capacity.





When adding diodes, buffer circuits (C-R), and other protections, they need to be installed near the MOS RELAY to be effective. Adding protection elements may result in a slow reset time, so adjust them according to the actual situation before use.

Note: When developing designs using this product, perform the expected performance of the equipment under the operating conditions recommended by the guidelines in this document. Continuous use under heavy loads (including, but not limited to, the application of high temperatures/current/voltage and significant changes in temperature, etc.) may result in deterioration of the reliability of this product.



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